

## Abstract

The invention relates to a novel process for producing a metal ceramic substrate, especially a copper-ceramic substrate, in which (process) at least one metal foil at a time is applied to the surface sides of a ceramic layer or a ceramic substrate using a high temperature bonding process and the metal foil is structured on at least one surface side for forming conductive tracks, contact surfaces, and the like.

## Abstract of the Disclosure

**[0041]** The invention relates to a novel process for producing a metal ceramic substrate, especially a copper-ceramic substrate, in which at least one metal foil at a time is applied to the surface sides of a ceramic layer or a ceramic substrate using a high temperature bonding process and the metal foil is structured on at least one surface side for forming conductive tracks, contact surfaces, and the like.